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Multilayer Ceramic Chip Capacitors

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Product Top Page Search by Part No. Search by Characteristics Cross Reference Catalog **Tech Notes** 

# C2012X7R1C105K125AA

TDK item description ?	C2012X7R1C105KT****
Applications	Commercial Grade  Please refer to Part No. CGA4J2X7R1C105K125AA for Automotive use.
Feature	General (Up to 75V)
Series	C2012 [EIA 0805]
Status	Production (Not Recommended for New Design)



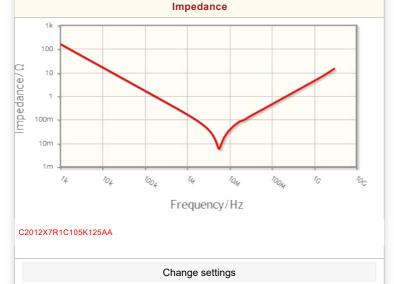
0000 Images are for reference only and show exemplary products.

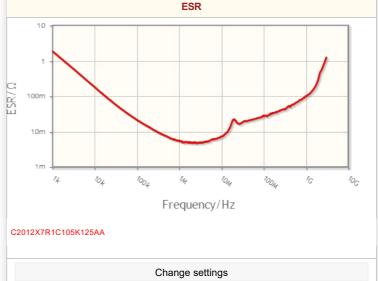
Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	1μF ±10%
Rated Voltage	16VDC
Temperature Characteristic ?	X7R(±15%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	100ΜΩ

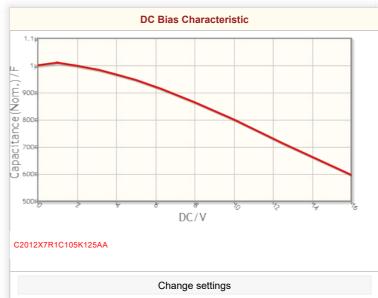
Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

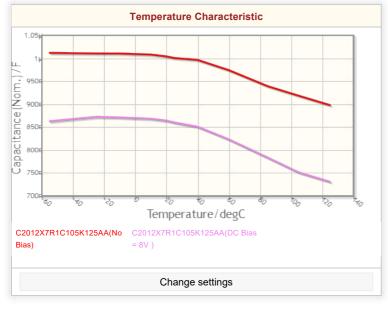
## Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

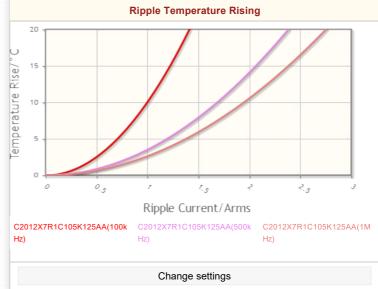














Selection Guide

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Distributor Inventory Chec

Cross Reference

EMC Components	
RF Components and Modules	
Voltage / Current / Temperature Protection Devices	
Sensors and Sensor Systems	
Ceramic Switching / Heating, Piezo Components, Buzzers and Microphones	
Transformers	
Ferrites and Accessories	
Noise Suppressing / Magnetic Sheet	
Anechoic Chambers and Radio Wave Absorbers	
Power Supplies	
Magnets	
Flash Storages	
Wireless Power Transfer	
FA Systems	
Transparent Conductive Film	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)	
Solar Cells	
Application Specific IC (ASIC) Development and Supply	

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